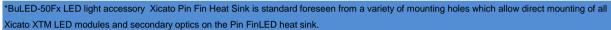


BULED

BuLED-50Fx LED light accessory to replace MR16 fittings by Xicato XTM

Features VS Benefits

- BuLED-50Fx LED light accessory includes one LED cooler and one LED housing to be assembled with Xicato XTM LED modules to replace MR16.
- * Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
- * Thermal resistance range Rth 5.0°C/W.
- * Xicato Thermal Class E , (60° tilt angle, 40°C ambient) .
- * The cooler design with mounting holes foreseen for direct mounting of Xicato XTM Module .
- * Heatsink Diameter 48mm Standard height 50mm, Other heights on request.
- * Housing Diameter 50mm Standard height 50mm , Other heights on request.
- * Forged from highly conductive aluminum.



In this way mechanical afterwork and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED coolers.

Below you find an overview of Xicato LED modules which standard fit on the BuLED-50Fx LED light accessory .

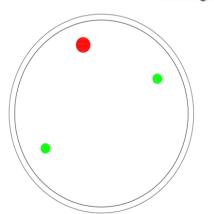
MingFa performs thermal validation tests on each of the LED modules mounted on the LED cooler and publishes.

This data in the Xicato Cooler thermal validation reports.

*For a full overview of avaliable LED coolers for Xicato LEDs, please refer to the Xicato LED cooler overview on.







BuLED-50Fx LED light accessory, The Heatsink standard height 50mm for Xicato LED modules Mounting Options

Xicato XTM LED modules:

XTM19-8027-xxx; XTM19-8030-xxx; XTM19-V830-xxx ;

XTM19-8035-xxx;

Direct mounting by Zhaga mounting holes with 2 screws M3 x 8mm; with Shinland Zhaga holder. Green indicator marks.

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Mounting Options and Drawings & Dimensions

Example:BuLED-50Fx-M3-B-2
Example:BuLED-50Fx-M3-

Anodising Color B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

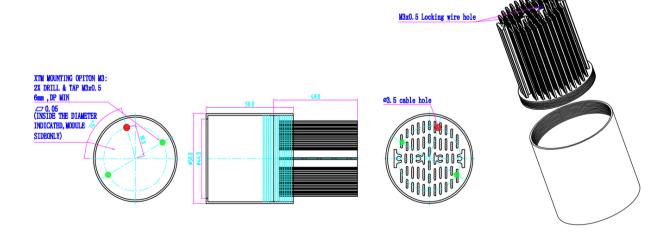
Ex.order code - 12

means option 1 and 2 combined

MingFa recommends the use of a high Thermal conductive interface between the LED Module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad Thickness 0.1-0.15mm is recommended.



MOUNTING OPTION	PART NUMBER	THREAD	THREAD DEPTH
NONE	BuLED-50Fx -M3-#-N	NONE	NONE
1	BuLED-50Fx -M3-#-1	Ф3.5	Through-hole Cable hole
2	BuLED-50Fx -M3-#-2	M3*0.5	Locking wire hole
3			



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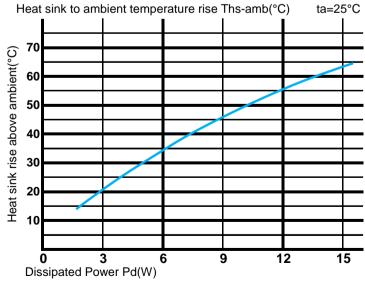




The thermal data table



Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		BuLED-50Fx	
Dissipated Power Pd(W)	3.0	7.0	21.0
	6.0	5.7	34.0
	9.0	5.1	46.0
	12.0	4.7	56.0
	15.0	4.2	63.0



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